

SSM 4A / SSM 9

Repair of through hole parts



SSM 4A / SSM9

The SSM machines are used for selective soldering and desoldering of multilead, through-hole technology components.

Due to the programmable parameters precise and repeatable results can be achieved, user-independent.

MAIN FEATURES

- Flexible solutions for **standard or irregular shaped components**
- **Repeatable soldering results due to defined process parameters** as soldering temperature, process time, wave height, ramp up and ramp down or regarding the SSM 9, up to 10 programmable parameters
- **Easy height adjustment** of the printed circuit board over the flow well
- Stable construction: **Easy to use and stable table top machine**
- Also **irregular shaped boards up to a size of 840 x 600 mm can be fixed** on the quick locking board holder
- **Blow out** option to clean the solder joints after removal of a connector
- **Application specific tooling** for any kind of component also on dense populated boards, including multi soldering solutions, for wetting of defined positions
- **Optional preheater module PH 4**, especially for the lead-free applications
- **Lead-free retrofit:** Already installed machines can be retrofitted for lead-free applications

SELECTIVE SOLDERING, THROUGH-HOLE TECHNOLOGY

Due to up to ten programmable parameters as soldering temperature, cycle time, wave height, ramp up and ramp down, precise and repeatable soldering results occur.



MARKET REQUIREMENT

Enhanced effectiveness

- Fast positioning with the air nozzle
- Soldering and desoldering at the same time/position
- Reliable blow-out of solder holes from above, immediately after removal of the device

Enhanced quality

- Precise adjustment of soldering parameters
- Reproducible results
- Non mechanical stress protects device and circuit board against damage
- Adjacent devices are protected during soldering process. Heat is isolated to a single component

APPLICATION RANGE

Repairs

Damaged components can be replaced.

Prototyping

Prototypes can be equipped and soldered in an efficient way with the SSM 4 and SSM 9.

Retrofits

- Components which are missing at production time
- On the soldering side components have to be placed
- A SMD equipped board has to be extended by single wired components

Soldering

When equipping boards with only few components the use of the soldering and desoldering machines SSM 4 or SSM 9 is in most cases the simplest and most economical way.

Saves time

The system's ergonomic design speeds up and simplifies your work and generates results that comply with the most stringent quality requirements.

No Restrictions

The SSM 4 and SSM 9 will dependably handle even the most difficult soldering and desoldering jobs:

- Operations on multilayer boards
- Processes components with complex geometries such as DIP switches and long connectors
- Operates on dense mixed technology boards
- Soldering on the assembly side, even between adjacent high components
- Soldering and desoldering of Pin Grid Arrays and sockets
- Soldering on flex boards



OPTIONAL PREHEATER MODULE PH 4

To improve the performance for lead-free applications

The preheater module PH 4 can be used as individual device or together with the SSM 4A or the SSM 9. By preheating the PCB before the selective soldering process is carried out the risk of copper delamination is reduced. The preheater PH 4 uses IR technology to preheat the printed circuit board on an area of 300 x 300 mm with a performance of 3500 watt.

SSM 4A

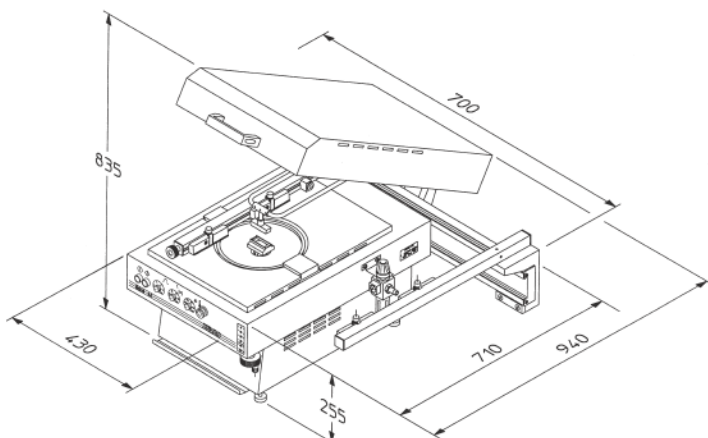
The SSM 4A is used for selective soldering and desoldering of multipolar trough hole components (THT). Due to defined process parameters repeatable results can be achieved.



TECHNICAL DATA

Product designation	SSM 4A
Max. board size	600 x 600 mm
Pumping system	Solder pump
Heat up time	Approx. 30 min
Cycle duration	0 - 60 s
Air pressure	1 - 8 bar
Solder temperature	200 °C - 300 °C
Max. power consumption	2500 Watt
Power requirements	220 - 230 Volt, 50 Hz
Dimensions (W x D x H)	440 x 800 x 360 mm
Solder content	Approx. 16 kg
Weight (without solder)	47 kg

DIMENSIONS



SSM 9

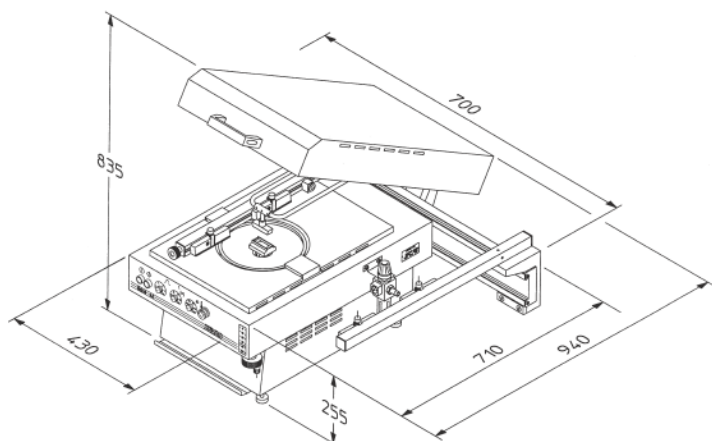
The SSM 9 is used for selective soldering and desoldering of multipolar trough hole components. Due to the programmable parameters precise and repeatable results can be achieved, user-independent



TECHNICAL DATA

Product designation	SSM 9
Max. board size	840 x 600 mm
Pumping system	Solder pump
Heat up time	Approx. 30 min
Cycle duration	0 - 60 s
Air pressure	1 - 8 bar
Solder temperature	235 °C - 400 °C
Max. power consumption	2500 Watt
Power requirements	220 - 230 Volt, 50 Hz
Dimensions (W x D x H)	440 x 800 x 360 mm
Solder content	Approx. 16 kg
Weight (without solder)	75 kg

DIMENSIONS





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